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APPLICANTS

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** CONTINUING DATA ***** *none K.N.*

** FOREIGN APPLICATIONS ***** *yes K.N.*
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35 USC 119 (a-d) conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance	COUNTRY	DRAWING	CLAIMS	CLAIMS
Verified and Acknowledged <i>K. Sakurai</i> Examiner's Signature Initials	JAPAN	2	7	2

ADDRESS

23373

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TITLE

Solder deposition method and solder bump forming method

FILING FEE	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT	<input type="checkbox"/> All Fees
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